## AMENDMENTS TO THE CLAIMS

Please amend the claims as follows:

1. (Currently Amended) A housing having a liquid-tight electric bushing comprising: ~~in which~~

an opening ~~(2) provided~~ in the housing; and ~~(1) is closed with a closure surrounding the electric bushing, characterized in that the closure is~~

a closure for the opening, the closure comprising a printed circuit board mounted to the housing and having at least first and second layers; ~~(3) embodied in multiple layers,~~ the first layer is a top side of the printed circuit board and spans the opening,

wherein a first contact element is disposed on the top side and in a bore through the first layer that extends to at least the second layer, and

wherein the second layer is a conductor track in the interior of the printed circuit board.

2. (Cancelled)

3. (Cancelled)

4. (Currently Amended) The housing as defined by claim 1~~one of the foregoing claims~~, wherein the first layer ~~(4)~~ is ~~produced from~~ an electrical insulation material.

5. (Currently Amended) The housing as defined by claim 1~~one of the foregoing claims~~, wherein the first contact element ~~(10)~~ is coupled ~~connected electrically~~ to a second contact element ~~(12)~~ via ~~at least~~ the second layer. ~~one conductor track, guided in the interior of the printed circuit board (3) and forming a second layer (5).~~

6. (Cancelled)

7. (Currently Amended) The housing as defined by claim 5~~one of the foregoing claims~~, wherein the second contact element ~~(12)~~ is ~~provided~~ on an underside ~~(U)~~ that is ~~located~~ opposite the top side ~~(O)~~.

8. (Currently Amended) The housing as defined by claim 5, ~~one of the foregoing claims~~, wherein the second contact element ~~(12)~~ extends ~~is extended to the~~ to an outside ~~at~~ an edge of the printed circuit board ~~(3)~~.

9. (Currently Amended) The housing as defined by claim 1, ~~one of the foregoing claims~~, wherein the printed circuit board ~~(3)~~ is flexible.

10. (Currently Amended) The housing as defined by claim 1, ~~one of the foregoing claims~~, wherein the printed circuit board ~~(3)~~ comprises ~~has~~ a plurality of second layers ~~(5)~~, located one above the other~~, of conductor tracks~~.

11. (Currently Amended) The housing as defined by claim 5, ~~one of the foregoing~~ claims, wherein the first contact element ~~(10)~~ and the second contact element ~~(12)~~ are coupled ~~connected~~ via a plurality of conductor tracks, which are located one above the other and are electrically coupled ~~connected~~. ~~to one another electrically conductively.~~

12. (Currently Amended) The housing as defined by claim 1, ~~one of the foregoing claims,~~ wherein a seal ~~(16)~~ is disposed ~~provided~~ between the printed circuit board ~~(3)~~ and the housing ~~(1)~~.

13. (Currently Amended) The housing as defined by claim 12, ~~one of the foregoing claims,~~ wherein a pressure plate contacts ~~(14) contacting~~ the underside ~~(U)~~ of the printed circuit board ~~(3) is provided for pressing~~ and presses the printed circuit board ~~(3)~~ against the seal ~~(16)~~.

14. (Currently Amended) The housing as defined by claim 1~~one of the foregoing claims,~~ wherein ~~in~~ the housing ~~(1),~~ further comprises an X-ray tube. ~~is received.~~

15. (Currently Amended) A method of using ~~The use of~~ a printed circuit board ~~(3)~~ ~~as a closure for liquid-tight closing~~ to close ~~of a~~ an opening ~~(2)~~ provided in a housing ~~(1)~~ and as an electric bushing comprising:

mounting the printed circuit board comprising a first layer on the housing, wherein the first layer spans the opening and is the top side of the printed circuit board, and

disposing a first contact element on the top side and through a bore in the top side, wherein the bore extends at least as far as a second layer formed in the printed circuit board as a conductor track.

16. (Cancelled)

17. (Cancelled)

18. (Currently Amended) The method ~~use~~ as defined by claim 15, ~~one of claims 15 through 17,~~ wherein the method further includes producing the first layer ~~(4) is produced~~ from an electrical insulation material.

19. (Currently Amended) The ~~use~~ method as defined by claim 15, ~~one of claims 15 through 18~~, wherein the method further comprises connecting the first contact element ~~(10) is connected electrically~~ to a second contact element ~~(12)~~ via the second layer. ~~the at least one conductor track, guided in the interior of the printed circuit board (3) and forming a second layer (5).~~

20. (Cancelled)

21. (Currently Amended) The method ~~use~~ as defined by claim 19, ~~one of claims 15 through 20,~~ wherein the method further comprises disposing the second contact element ~~(12) is provided~~ on an underside that is ~~(U) located~~ opposite the top side ~~(O)~~.

22. (Currently Amended) The method ~~use~~ as defined by claim 19, ~~one of claims 15 through 21,~~ wherein the method further comprises extending the second contact element ~~(12) is extended~~ to an ~~the~~ outside ~~at an~~ edge of the printed circuit board ~~(3)~~.

23. (Currently Amended) The method ~~use~~ as defined by claim 15, ~~one of claims 15 through 22,~~ wherein the method further comprises using the printed circuit board ~~(3)~~ that is flexible.

24. (Currently Amended) The method ~~use~~ as defined by claim 15, ~~one of claims 15~~

~~through 23~~, wherein the method comprises using the printed circuit board ~~(3)~~ that has a plurality of second layers ~~(5),~~ located one above the other ~~of conductor tracks.~~

25. (Currently Amended) The method ~~use~~ as defined by claim 24, ~~one of claims 15 through 24,~~ wherein the first contact element ~~(10)~~ and ~~the~~a second contact element ~~(12)~~ are connected via a plurality of conductor tracks in alignment with each other. ~~, located one above the other and connected to one another electrically conductively.~~

26. (Currently Amended) The method ~~use~~ as defined by claim 15, ~~one of claims 15 through 25,~~ wherein the method comprises disposing a seal ~~(16) is provided~~ between the printed circuit board ~~(3)~~ and the housing ~~(1)~~.

27. (Currently Amended) The method ~~use~~ as defined by claim 26, ~~one of claims 15 through 26,~~ wherein the method comprises using a pressure plate that contacts ~~(14) contacting~~ the underside ~~(U)~~ of the printed circuit board and presses ~~(3) is provided for pressing~~ the printed circuit board ~~(3)~~ against the seal ~~(16)~~.

28. (Currently Amended) The method ~~use~~ as defined by claim 15, ~~one of claims 15 through 27,~~ wherein the method further comprises using ~~in the housing (1),~~ an X-ray tube in the housing. ~~is received.~~